

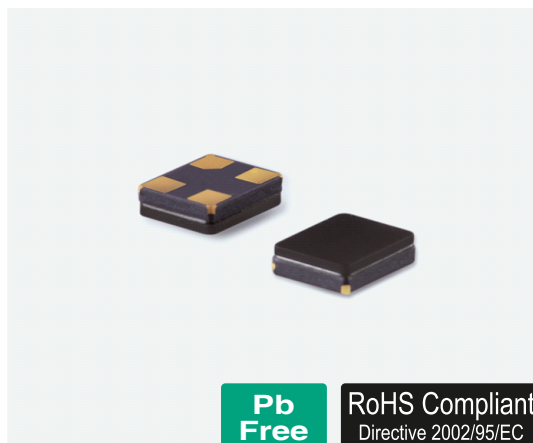
# 3XG Series 3.2x2.5 SMD Glass Sealed Crystal

## FEATURE

- Rugged AT-cut crystal construction.
- Miniature 3.2x2.5mm ceramic package.
- Designed for automatic mounting and reflow soldering.
- Embossed taping specification.
- Pb-free and RoHS/Green compliant.

## APPLICATIONS

- Ideally suited designed for Bluetooth wireless communication sets, HDD, DSN, PDA, GPS, Digital Tuner, Wireless LAN and mobile phone.



## Electrical Specifications 电气参数

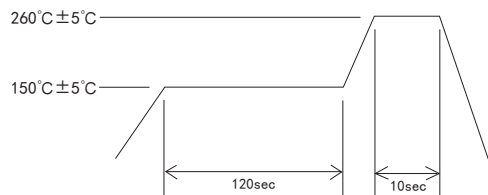
型号	Holder Type	3.2x2.5mm Glass Surface Mount
频率范围	Frequency Range	12.000MHz to 54.000MHz
调整频差	Frequency Tolerance ( $\Delta F$ ) (at 25°C)	$\pm 10$ ppm to $\pm 30$ ppm
温度频差	Frequency Drift	$\pm 10$ ppm to $\pm 30$ ppm※(See Notes)
工作温度范围	Operating Temperature Range	-20°C - +70°C / -40°C - +85°C
储存温度范围	Storage Temperature Range	-40°C - +85°C / -55°C - +125°C
老化	Aging (25°C)	$\pm 3$ ppm/ year max.
静电容	Shunt Capacitance (C0)	3pF max.
激励功率	Drive Level	10 $\mu$ w (100 $\mu$ W max.)
绝缘阻抗	Insulation Resistance (Rs)	500 Megaohms Minimum at D.C.100V
负载电容	Load Capacitance (CL)	Suggested by customer

※Notes:  $\pm 10$ ,  $\pm 20$ ,  $\pm 30$ ppm (-20°C to +70°C)  
 $\pm 20$ ,  $\pm 30$ ,  $\pm 50$ ppm (-40°C to +85°C) or depends on customer

## Equivalent Series Resistance and Mode of Operation 等效阻抗和振荡模式

Frequency Range 频率范围	ESR ( $\Omega$ ) 等效阻抗	Mode 振荡模式
12.000MHz $\leq f < 16.000$ MHz	100 $\Omega$ max	Fundamental
16.000MHz $\leq f < 20.000$ MHz	80 $\Omega$ max	Fundamental
20.000MHz $\leq f < 24.000$ MHz	60 $\Omega$ max	Fundamental
24.000MHz $\leq f < 54.000$ MHz	40 $\Omega$ max	Fundamental

## Reflow Condition(回流焊条件)



CYCLE TIME: 200sec Max.

## Mechanical Dimensions 外型尺寸

